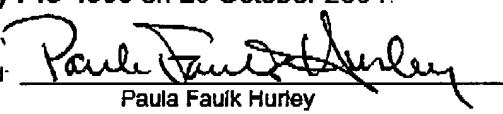


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Paula Faulk Hurley

ATTORNEY DOCKET: CPAC 1017-4 D2

No. 0975 P. 1

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Karnezos

Attorney Docket No.: CPAC 1017-4 D2

Application No.: 10/632,551

Examiner: Jasmine Clark

Filed: 02 August 2003

Group: 2811

Title: Semiconductor Multi-Package
Module Having Wire Bond Interconnect
Between Stacked Packages And Having
Electrical Shield

Confirmation No.: 2571

Customer No. 22470

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Commissioner for Patents
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SUBMISSION OF PRIOR ART AFTER NOTICE OF ALLOWANCE

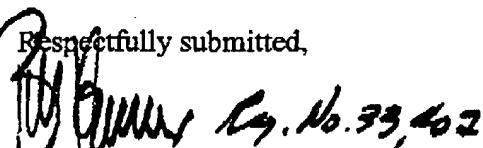
Sir:

Applicants submit the below-listed documents to be placed in the file:

- Lin; U.S. Patent No. 5,436,203 issued 25 July 1995 for "Shielded Liquid Encapsulated Semiconductor Device and Method for Making the Same".
- Mori; U.S. Patent No. 5,903,049 issued 11 May 1999 for "Semiconductor Module Comprising Semiconductor Packages".
- Ozawa et al; U.S. Patent No. 6,316,838 issued 13 November 2001 for "Semiconductor Device".
- Kakimoto et al.; U.S. Patent No. 6,333,552 issued 25 December 2001 for "Millimeter Wave Semiconductor Device".

- Terui; U.S. Patent No. 6,472,732 issued 29 October 2002 for "BGA Package and Method for Fabricating the Same".
- Kikuma et al.; U.S. Patent No. 6,777,799 issued 17 August 2004 for "Stacked Semiconductor Device and Method of Producing the Same".

Respectfully submitted,


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Date: 26 October 2004

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